

MC74HC164B

8-Bit Serial-Input/Parallel-Output Shift Register

High-Performance Silicon-Gate CMOS

The MC74HC164B is identical in pinout to the LS164. The device inputs are compatible with standard CMOS outputs; with pullup resistors, they are compatible with LSTTL outputs.

The MC74HC164B is an 8-bit, serial-input to parallel-output shift register. Two serial data inputs, A1 and A2, are provided so that one input may be used as a data enable. Data is entered on each rising edge of the clock. The active-low asynchronous Reset overrides the Clock and Serial Data inputs. Schmitt-trigger action at the Clock input enhances the device's tolerance to slower rise and fall times and immunity to noise of the input clock signal.

Features

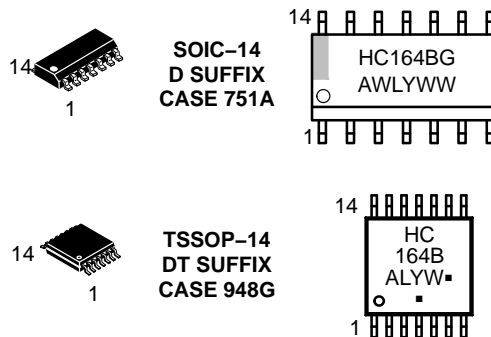
- Output Drive Capability: 10 LSTTL Loads
- Outputs Directly Interface to CMOS, NMOS, and TTL
- Operating Voltage Range: 2.0 V to 6.0 V
- Low Input Current: 1 μ A
- High Noise Immunity Characteristic of CMOS Devices
- In Compliance with the JEDEC Standard No. 7 A Requirements
- Chip Complexity: 244 FETs or 61 Equivalent Gates
- NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant



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MARKING DIAGRAMS



A = Assembly Location
L, WL = Wafer Lot
Y = Year
W, WW = Work Week
G or ■ = Pb-Free Package

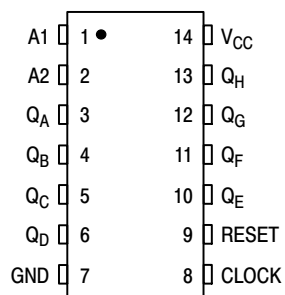
(Note: Microdot may be in either location)

ORDERING INFORMATION

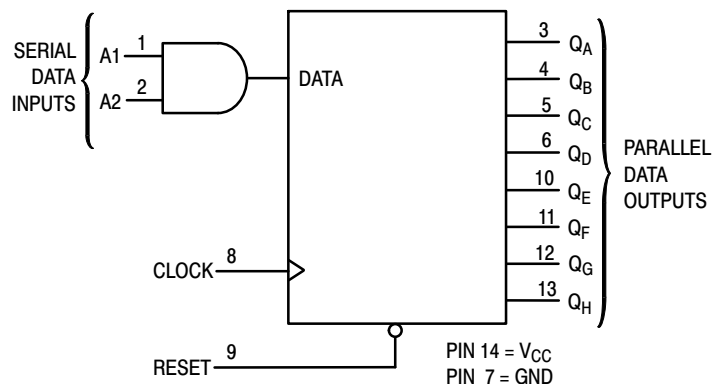
See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

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PIN ASSIGNMENT



LOGIC DIAGRAM



FUNCTION TABLE

Inputs				Outputs			
Reset	Clock	A1	A2	QA	QB	...	QH
L	X	X	X	L	L	...	L
H		X	X	No Change			
H		H	D	D	QA _n	...	QG _n
H		D	H	D	QA _n	...	QG _n

D = data input

QA_n – QG_n = data shifted from the preceding stage on a rising edge at the clock input.

ORDERING INFORMATION

Device	Package	Shipping†
MC74HC164BDG	SOIC-14 (Pb-Free)	55 Units / Rail
MC74HC164BDR2G		2500 / Tape & Reel
NLV74HC164BDR2G*		2500 / Tape & Reel
MC74HC164BDTR2G	TSSOP-14 (Pb-Free)	2500 / Tape & Reel
NLV74HC164BDTR2G*		2500 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

*NLV Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q100 Qualified and PPAP Capable

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MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V_{CC}	DC Supply Voltage (Referenced to GND)	- 0.5 to + 7.0	V
V_{in}	DC Input Voltage (Referenced to GND)	- 0.5 to $V_{CC} + 0.5$	V
V_{out}	DC Output Voltage (Referenced to GND)	- 0.5 to $V_{CC} + 0.5$	V
I_{in}	DC Input Current, per Pin	± 20	mA
I_{out}	DC Output Current, per Pin	± 25	mA
I_{CC}	DC Supply Current, V_{CC} and GND Pins	± 50	mA
P_D	Power Dissipation in Still Air, SOIC Package† TSSOP Package†	500 450	mW
T_{stg}	Storage Temperature	- 65 to + 150	°C
T_L	Lead Temperature, 1 mm from Case for 10 Seconds (SOIC or TSSOP Package)	260	°C

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high-impedance circuit. For proper operation, V_{in} and V_{out} should be constrained to the range $GND \leq (V_{in} \text{ or } V_{out}) \leq V_{CC}$. Unused inputs must always be tied to an appropriate logic voltage level (e.g., either GND or V_{CC}). Unused outputs must be left open.

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

†Derating — SOIC Package: - 7 mW/°C from 65° to 125°C
TSSOP Package: - 6.1 mW/°C from 65° to 125°C

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit	
V_{CC}	DC Supply Voltage (Referenced to GND)	2.0	6.0	V	
V_{in}, V_{out}	DC Input Voltage, Output Voltage (Referenced to GND)	0	V_{CC}	V	
T_A	Operating Temperature, All Package Types	- 55	+ 125	°C	
t_r, t_f	Input Rise and Fall Time (Figure 1)	$V_{CC} = 2.0 \text{ V}$ $V_{CC} = 4.5 \text{ V}$ $V_{CC} = 6.0 \text{ V}$	0 0 0	No Limit No Limit No Limit	ns

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

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DC ELECTRICAL CHARACTERISTICS (Voltages Referenced to GND)

Symbol	Parameter	Test Conditions	V _{CC} V	Guaranteed Limit			Unit
				-55°C to 25°C	≤ 85°C	≤ 125°C	
V _{T+} max	Maximum Positive-Going Input Threshold Voltage (Figure 3)	V _{out} = 0.1V I _{out} ≤ 20μA	2.0	1.50	1.50	1.50	V
			3.0	2.15	2.15	2.15	
			4.5	3.15	3.15	3.15	
			6.0	4.20	4.20	4.20	
V _{T+} min	Minimum Positive-Going Input Threshold Voltage (Figure 3)	V _{out} = 0.1V I _{out} ≤ 20μA	2.0	1.0	0.95	0.95	V
			3.0	1.5	1.45	1.45	
			4.5	2.3	2.25	2.25	
			6.0	3.0	2.95	2.95	
V _{T-} max	Maximum Negative-Going Input Threshold Voltage (Figure 3)	V _{out} = V _{CC} - 0.1V I _{out} ≤ 20μA	2.0	0.9	0.95	0.95	V
			3.0	1.4	1.45	1.45	
			4.5	2.0	2.05	2.05	
			6.0	2.6	2.65	2.65	
V _{T-} min	Minimum Negative-Going Input Threshold Voltage (Figure 3)	V _{out} = V _{CC} - 0.1V I _{out} ≤ 20μA	2.0	0.3	0.3	0.3	V
			3.0	0.5	0.5	0.5	
			4.5	0.9	0.9	0.9	
			6.0	1.2	1.2	1.2	
V _H max (Note 1)	Maximum Hysteresis Voltage (Figure 3)	V _{out} = 0.1V or V _{CC} - 0.1V I _{out} ≤ 20μA	2.0	1.20	1.20	1.20	V
			3.0	1.65	1.65	1.65	
			4.5	2.25	2.25	2.25	
			6.0	3.00	3.00	3.00	
V _H min (Note 1)	Minimum Hysteresis Voltage (Figure 3)	V _{out} = 0.1V or V _{CC} - 0.1V I _{out} ≤ 20μA	2.0	0.20	0.20	0.20	V
			3.0	0.25	0.25	0.25	
			4.5	0.40	0.40	0.40	
			6.0	0.50	0.50	0.50	
V _{OH}	Minimum High-Level Output Voltage	V _{in} = V _{IH} or V _{IL} I _{out} ≤ 20 μA	2.0	1.9	1.9	1.9	V
			4.5	4.4	4.4	4.4	
			6.0	5.9	5.9	5.9	
			V _{in} = V _{IH} or V _{IL} I _{out} ≤ 2.4 mA	3.0	2.48	2.34	
I _{out} ≤ 4.0 mA	4.5	3.98	3.84	3.70			
I _{out} ≤ 5.2 mA	6.0	5.48	5.34	5.20			
V _{OL}	Maximum Low-Level Output Voltage	V _{in} = V _{IH} or V _{IL} I _{out} ≤ 20 μA	2.0	0.1	0.1	0.1	V
			4.5	0.1	0.1	0.1	
			6.0	0.1	0.1	0.1	
			V _{in} = V _{IH} or V _{IL} I _{out} ≤ 2.4 mA	3.0	0.26	0.33	
I _{out} ≤ 4.0 mA	4.5	0.26	0.33	0.40			
I _{out} ≤ 5.2 mA	6.0	0.26	0.33	0.40			
I _{in}	Maximum Input Leakage Current	V _{in} = V _{CC} or GND	6.0	± 0.1	± 1.0	± 1.0	μA
I _{CC}	Maximum Quiescent Supply Current (per Package)	V _{in} = V _{CC} or GND I _{out} = 0 μA	6.0	4	40	160	μA

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

1. V_Hmin > (V_{T+} min) - (V_{T-} max); V_Hmax = (V_{T+} max) - (V_{T-} min).

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AC ELECTRICAL CHARACTERISTICS (C_L = 50 pF, Input t_r = t_f = 6 ns)

Symbol	Parameter	V _{CC} V	Guaranteed Limit			Unit
			-55°C to 25°C	≤ 85°C	≤ 125°C	
f _{max}	Maximum Clock Frequency (50% Duty Cycle) (Figures 1 and 4)	2.0	10	10	10	MHz
		3.0	20	20	20	
		4.5	40	35	30	
		6.0	50	45	40	
t _{PLH} , t _{PHL}	Maximum Propagation Delay, Clock to Q (Figures 1 and 4)	2.0	160	200	250	ns
		3.0	100	150	200	
		4.5	32	40	48	
		6.0	27	34	42	
t _{PHL}	Maximum Propagation Delay, Reset to Q (Figures 2 and 4)	2.0	175	220	260	ns
		3.0	100	150	200	
		4.5	35	44	53	
		6.0	30	37	45	
t _{TLH} , t _{THL}	Maximum Output Transition Time, Any Output (Figures 1 and 4)	2.0	75	95	110	ns
		3.0	27	32	36	
		4.5	15	19	22	
		6.0	13	16	19	
C _{in}	Maximum Input Capacitance	—	10	10	10	pF
C _{PD}	Power Dissipation Capacitance (Per Package)*	Typical @ 25°C, V _{CC} = 5.0 V			pF	
		180				

TIMING REQUIREMENTS (Input t_r = t_f = 6 ns)

Symbol	Parameter	V _{CC} V	Guaranteed Limit			Unit
			-55°C to 25°C	≤ 85°C	≤ 125°C	
t _{su}	Minimum Setup Time, A1 or A2 to Clock (Figure 3)	2.0	25	35	40	ns
		3.0	15	20	25	
		4.5	7	8	9	
		6.0	5	6	6	
t _h	Minimum Hold Time, Clock to A1 or A2 (Figure 3)	2.0	3	3	3	ns
		3.0	3	3	3	
		4.5	3	3	3	
		6.0	3	3	3	
t _{rec}	Minimum Recovery Time, Reset Inactive to Clock (Figure 2)	2.0	3	3	3	ns
		3.0	3	3	3	
		4.5	3	3	3	
		6.0	3	3	3	
t _w	Minimum Pulse Width, Clock (Figure 1)	2.0	50	60	75	ns
		3.0	26	35	45	
		4.5	12	15	20	
		6.0	10	12	15	
t _w	Minimum Pulse Width, Reset (Figure 2)	2.0	50	60	75	ns
		3.0	26	35	45	
		4.5	12	15	20	
		6.0	10	12	15	

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PIN DESCRIPTIONS

INPUTS

A1, A2 (Pins 1, 2)

Serial Data Inputs. Data at these inputs determine the data to be entered into the first stage of the shift register. For a high level to be entered into the shift register, both A1 and A2 inputs must be high, thereby allowing one input to be used as a data–enable input. When only one serial input is used, the other must be connected to V_{CC} .

Clock (Pin 8)

Shift Register Clock. A positive–going transition on this pin shifts the data at each stage to the next stage. The shift

register is completely static, allowing clock rates down to DC in a continuous or intermittent mode.

OUTPUTS

$Q_A - Q_H$ (Pins 3, 4, 5, 6, 10, 11, 12, 13)

Parallel Shift Register Outputs. The shifted data is presented at these outputs in true, or noninverted, form.

CONTROL INPUT

Reset (Pin 9)

Active–Low, Asynchronous Reset Input. A low voltage applied to this input resets all internal flip–flops and sets Outputs $Q_A - Q_H$ to the low level state.

SWITCHING WAVEFORMS

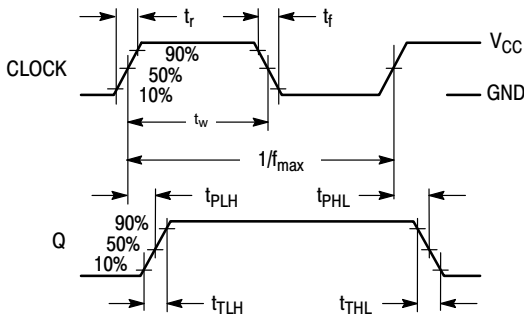


Figure 1.

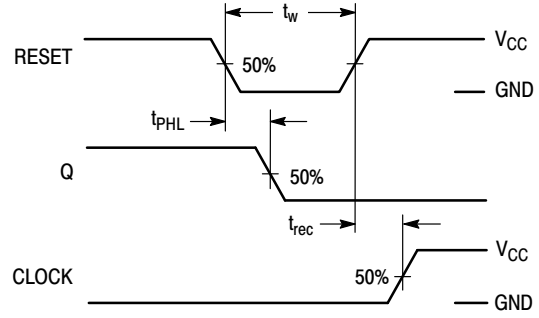


Figure 2.

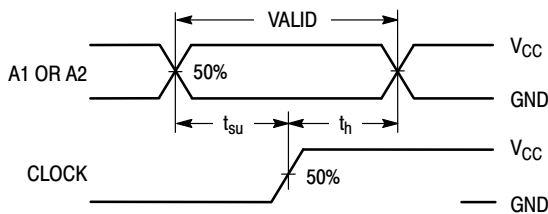
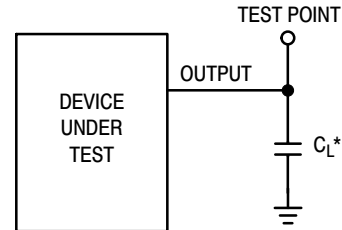


Figure 3.

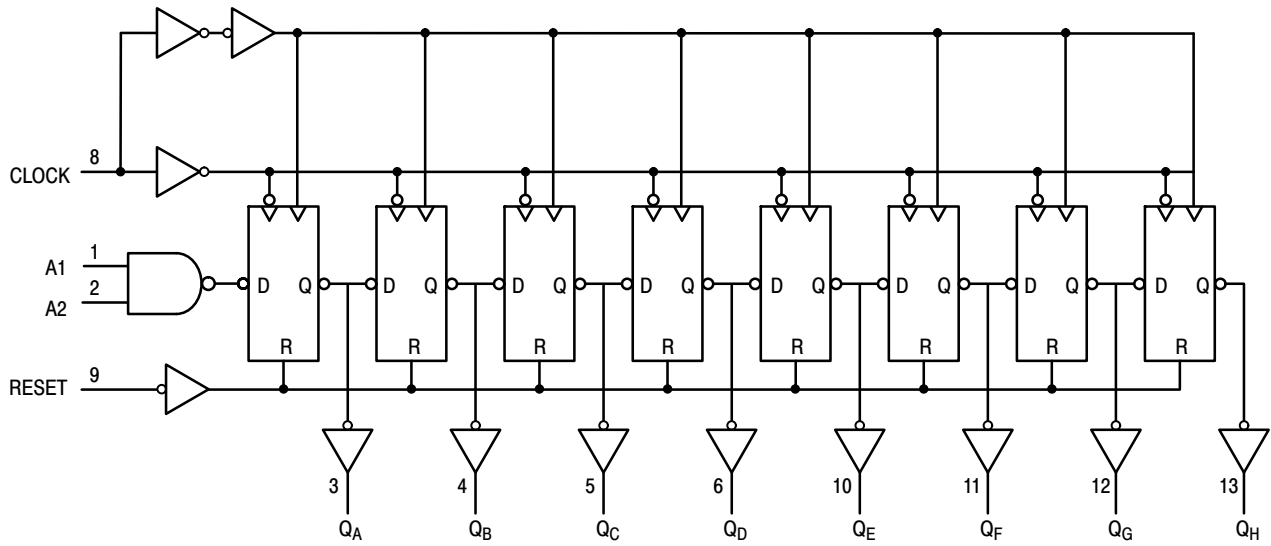


*Includes all probe and jig capacitance

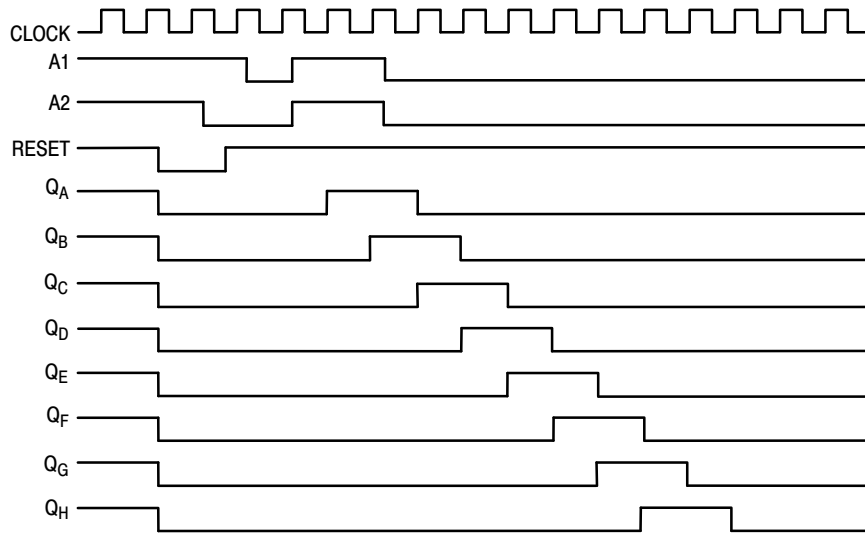
Figure 4. Test Circuit

MC74HC164B

EXPANDED LOGIC DIAGRAM

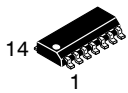


TIMING DIAGRAM



MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS

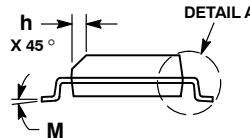
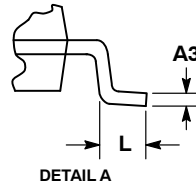
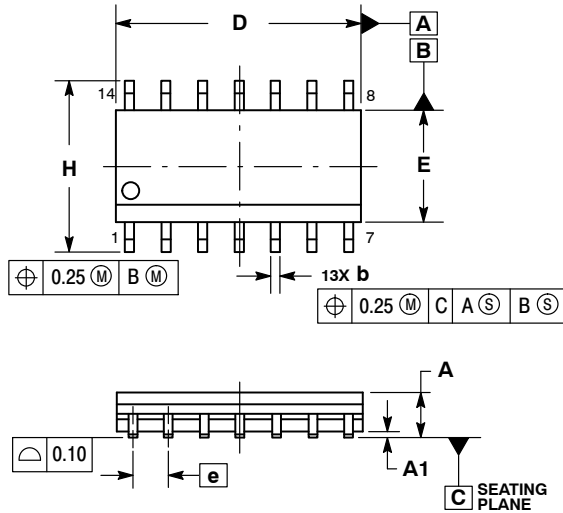
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SCALE 1:1

SOIC-14 NB
CASE 751A-03
ISSUE L

DATE 03 FEB 2016

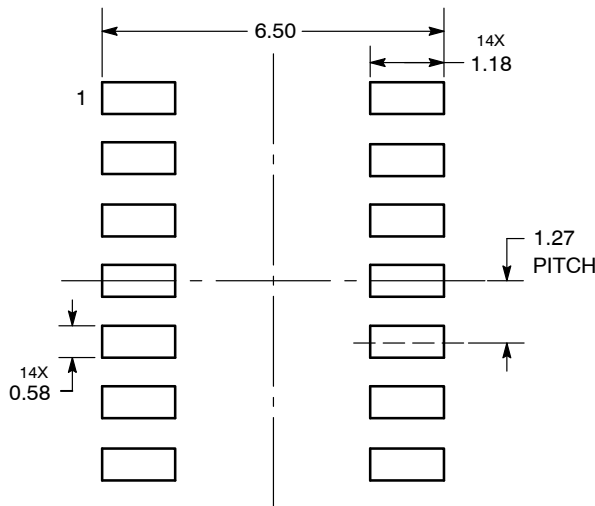


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF AT MAXIMUM MATERIAL CONDITION.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSIONS.
5. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	1.35	1.75	0.054	0.068
A1	0.10	0.25	0.004	0.010
A3	0.19	0.25	0.008	0.010
b	0.35	0.49	0.014	0.019
D	8.55	8.75	0.337	0.344
E	3.80	4.00	0.150	0.157
e	1.27 BSC		0.050 BSC	
H	5.80	6.20	0.228	0.244
h	0.25	0.50	0.010	0.019
L	0.40	1.25	0.016	0.049
M	0°	7°	0°	7°

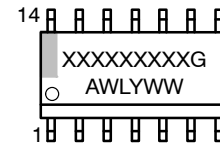
SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



- XXXXXX = Specific Device Code
- A = Assembly Location
- WL = Wafer Lot
- Y = Year
- WW = Work Week
- G = Pb-Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "▪", may or may not be present.

STYLES ON PAGE 2

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SOIC-14
CASE 751A-03
ISSUE L

DATE 03 FEB 2016

STYLE 1:
 PIN 1. COMMON CATHODE
 2. ANODE/CATHODE
 3. ANODE/CATHODE
 4. NO CONNECTION
 5. ANODE/CATHODE
 6. NO CONNECTION
 7. ANODE/CATHODE
 8. ANODE/CATHODE
 9. ANODE/CATHODE
 10. NO CONNECTION
 11. ANODE/CATHODE
 12. ANODE/CATHODE
 13. NO CONNECTION
 14. COMMON ANODE

STYLE 2:
 CANCELLED

STYLE 3:
 PIN 1. NO CONNECTION
 2. ANODE
 3. ANODE
 4. NO CONNECTION
 5. ANODE
 6. NO CONNECTION
 7. ANODE
 8. ANODE
 9. ANODE
 10. NO CONNECTION
 11. ANODE
 12. ANODE
 13. NO CONNECTION
 14. COMMON CATHODE

STYLE 4:
 PIN 1. NO CONNECTION
 2. CATHODE
 3. CATHODE
 4. NO CONNECTION
 5. CATHODE
 6. NO CONNECTION
 7. CATHODE
 8. CATHODE
 9. CATHODE
 10. NO CONNECTION
 11. CATHODE
 12. CATHODE
 13. NO CONNECTION
 14. COMMON ANODE


STYLE 5:
 PIN 1. COMMON CATHODE
 2. ANODE/CATHODE
 3. ANODE/CATHODE
 4. ANODE/CATHODE
 5. ANODE/CATHODE
 6. NO CONNECTION
 7. COMMON ANODE
 8. COMMON CATHODE
 9. ANODE/CATHODE
 10. ANODE/CATHODE
 11. ANODE/CATHODE
 12. ANODE/CATHODE
 13. NO CONNECTION
 14. COMMON ANODE

STYLE 6:
 PIN 1. CATHODE
 2. CATHODE
 3. CATHODE
 4. CATHODE
 5. CATHODE
 6. CATHODE
 7. CATHODE
 8. ANODE
 9. ANODE
 10. ANODE
 11. ANODE
 12. ANODE
 13. ANODE
 14. ANODE

STYLE 7:
 PIN 1. ANODE/CATHODE
 2. COMMON ANODE
 3. COMMON CATHODE
 4. ANODE/CATHODE
 5. ANODE/CATHODE
 6. ANODE/CATHODE
 7. ANODE/CATHODE
 8. ANODE/CATHODE
 9. ANODE/CATHODE
 10. ANODE/CATHODE
 11. COMMON CATHODE
 12. COMMON ANODE
 13. ANODE/CATHODE
 14. ANODE/CATHODE

STYLE 8:
 PIN 1. COMMON CATHODE
 2. ANODE/CATHODE
 3. ANODE/CATHODE
 4. NO CONNECTION
 5. ANODE/CATHODE
 6. ANODE/CATHODE
 7. COMMON ANODE
 8. COMMON ANODE
 9. ANODE/CATHODE
 10. ANODE/CATHODE
 11. NO CONNECTION
 12. ANODE/CATHODE
 13. ANODE/CATHODE
 14. COMMON CATHODE

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